



Hybrid and Heterogeneous Integration on Photonic Circuits: New Opportunities for Multifunctional Photonic Platforms

Guest Editor:

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Message from the Guest Editor

Dear Colleagues,

The field of Silicon Photonics has rapidly evolved over the last few years, supported by the gain in maturity of the technology, design tools, and methods employed. Despite the fact that indium phosphide (InP) and silicon-on-insulator (SOI) platforms are still considered as the warhorses of integrated photonics in terms of maturity and deployment of active (InP) and passive (SOI) components, other alternatives such as germanium-on-silicon, silicon nitride-on-insulator or hybrid solutions combining different functional materials and Si are gaining momentum. A representative example is the hybrid III-V/Si platform, which has been used to develop on-chip tunable lasers for wavelength division multiplexing purposes.

This Special Issue will focus on recent advancements on hybrid and heterogeneous photonic circuits spanning from materials, processing techniques, and implementation of novel components, devices, and circuits employing diverse materials to enable multifunctional photonic platforms. With a combination of invited and contributed papers, this issue will survey the state-of-the-art of hybrid and heterogeneous photonic circuit technology.





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Message from the Editor-in-Chief

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